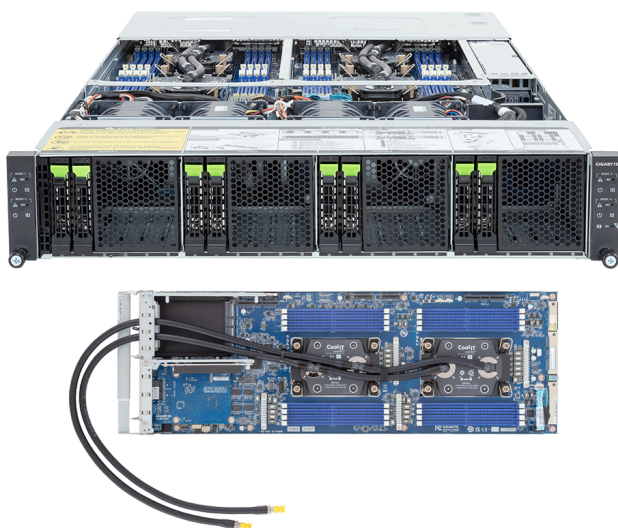


# H274-S61-LAW1

High Density Server - Intel® Xeon® 6 -  
2U 4-Node DP 8-Bay Gen5 NVMe/SATA/SAS-4 DLC



## Key Features

- Direct liquid cooling solution
- 2U 4-node rear access server system
- Dual Intel® Xeon® 6700/6500-Series Processors per node
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs per node
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

## Applications

High-Performance Computing Server, High Converged Server, Servers for Hybrid/Private Cloud...

## Specification

<b>Dimensions</b>	2U 4-Node - Rear access (W440 x H87.5 x D877 mm)	<b>PCIe Expansion Slots</b>	4 x LP PCIe Gen5 x16 4 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
<b>Motherboard</b>	MS64-HD0	<b>I/O Ports</b>	<b>Front:</b> 1 x CMC status LED, 1 x CMC reset button <b>Rear:</b> 8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN
<b>CPU</b>	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processor per node, TDP up to 350W at 35°C ambient	<b>Backplane Board</b>	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
<b>OS Compatibility</b>	<a href="#">OS Support List</a>	<b>TPM</b>	4 x TPM header (SPI), Optional TPM2.0 kit: CTM012 4 x PRoT connectors (only enabled on RoT SKU)
<b>Socket</b>	8 x LGA 4710 (Socket E2)	<b>Power Supply</b>	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V  *The system power supply requires C19 power cord.
<b>Chipset</b>	System on Chip	<b>System Fans</b>	4 x 80x80x80mm
<b>Memory</b>	8-Channel DDR5 RDIMM/MRDIMM, 64 x DIMMs [RDIMM] Up to 6400 MT/s [MRDIMM] Up to 8000 MT/s [1]  [1] MRDIMMs are supported only on select Intel® Xeon® 6 processors with P-cores.	<b>Operating Properties</b>	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)  *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
<b>LAN</b>	8 x 1Gb/s LAN (4 x Intel® I350-AM2), Support NCSI 4 x 10/100/1000 Mbps Management LAN	<b>Packaging Content</b>	1 x H274-S61-LAW1 8 x CoolIT CPU cold plate loops 1 x Mini-DP to D-Sub cable 16 x Carriers 1 x 3-Section Rail kit
<b>Video</b>	Integrated in ASPEED® AST2600 x 4 - 4 x Mini-DP	<b>Ordering Part Numbers</b>	6NH274S61DR000LAW1*
<b>Storage</b>	<b>Front hot-swap:</b> 8 x 2.5" Gen5 NVMe/SATA/SAS-4 [1] <b>Optional internal M.2:</b> 4 x M.2 (2260/2280/22110), PCIe Gen4 x4  [1] SAS card is required to support SAS drives.	<b>Optional Parts</b>	- M.2 riser card - CMTP160: 9CMTP160NR-00* - CoolIT leak sensor board: 6NH274S60S1000LAW10 (QPA:4)
<b>RAID</b>	Require RAID add-in cards Onboard VROC key headers		



Learn more at: <https://www.gigabyte.com/Enterprise>

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